IN THE CLAIMS:

Please amend the claims as follows:

1. (Canceled)

2. (Canceled)

3. (Previously Presented) A heat-resistant film comprising a film substrate and a heat-resistant slip layer disposed on one surface of the film substrate, the heat-resistant slip layer comprising a binder and a slip additive, wherein the slip additive is a higher fatty acid metal salt composition comprising a free higher fatty acid in an amount of 3 to 30wt% and a metal salt of a higher fatty acid, and wherein the binder is polymethylmethacrylate.

4. (Canceled)

5. (Previously Presented) A heat-resistant film comprising a film substrate and a heat-resistant slip layer disposed on one surface of the film substrate, the heat-resistant slip layer comprising a binder and a slip additive, wherein the slip additive is a higher fatty acid metal salt composition comprising a free higher fatty acid in an amount of 3 to 30wt% and a metal salt of a higher fatty acid, and wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

6. (Canceled)

7. (Previously Presented) The heat-resistant film according to claim 3, wherein the heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.

8. (Previously Presented) The heat-resistant film according to claim 3, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

9. (Previously Presented) The heat-resistant film according to claim 5, wherein the heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.

10-12. (Canceled)

13. (Previously Presented) The heat-resistant film according to claim 7, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

14-18. (Canceled)

19. (Previously Presented) A thermal transfer recording medium including a film substrate and a thermal transfer ink layer disposed on one surface of the film substrate and a heat-resistant slip layer disposed on the other surface of the film substrate, the heat-resistant slip layer comprising a binder and a slip additive, wherein the slip additive is a higher fatty acid metal salt composition comprising a free higher fatty acid in an amount of 3 to 30wt% and a metal salt of a higher fatty acid, and wherein the binder is polymethylmethacrylate.

20. (Canceled)

21. (Previously Presented) A thermal transfer recording medium including a film substrate and a thermal transfer ink layer disposed on one surface of the film substrate and a heat-resistant slip layer disposed on the other surface of the film substrate, the heat-resistant slip layer comprising a binder and a slip additive, wherein the slip additive is a higher fatty acid metal salt composition comprising a free higher fatty acid in an amount of 3 to 30wt% and a metal salt of a higher fatty acid, and wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

22. (Previously Presented) The heat-resistant film according to claim 3, wherein the

free higher fatty acid is stearic acid and the metal salt of higher fatty acid is aluminum stearate.

23. (Previously Presented) The heat-resistant film according to claim 5, wherein the free higher fatty acid is stearic acid and the metal salt of higher fatty acid is aluminum stearate.

24. (Previously Presented) The heat-resistant film according to claim 22, wherein the heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.

25. (Previously Presented) The heat-resistant film according to claim 22, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

26. (Previously Presented) The heat-resistant film according to claim 23, wherein the heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.